

Major memory manufacturer qualifies AIXTRON's QXP-8300 mini-batch ALD system

AIXTRON reaches important milestone for its silicon semiconductor manufacturing technology

Herzogenrath/Germany, September 12, 2016 – AIXTRON SE (FSE: AIXA; NASDAQ: AIXG), a worldwide leading provider of advanced deposition equipment to the semiconductor industry, announced today that a major memory manufacturer has qualified its QXP-8300 Atomic Layer Deposition (ALD) mini-batch system suitable for high-k oxide films in various advanced memory applications including 3D structure devices.

"We are delighted that our customer has completed the evaluation of our QXP-8300 ALD system for the manufacturing of the most advanced high performance memory devices. The QXP-8300 ALD system enables the manufacturing of advanced films with excellent electrical and device properties. AIXTRON is looking forward to further support its customer's memory development plans by providing the production equipment to address the challenges of a rapidly evolving industry," says Bill Bentinck, Vice President and General Manager of AIXTRON Inc., USA.

As the semiconductor memory cell size continues to be scaled down, manufacturers need advanced technologies for the deposition of precise layers of dielectric, metal and non-volatile memory materials. AIXTRON's QXP-8300 ALD system includes the patented TriJet vaporizer technology integrated with the unique close coupled showerhead design that enables the use of low vapor pressure precursors as needed in making higher-k dielectrics and metal nitrides for the performance improvement.

About AIXTRON

AIXTRON SE is a leading provider of deposition equipment to the semiconductor industry. The Company was founded in 1983 and is headquartered in Herzogenrath (near Aachen), Germany, with subsidiaries and sales offices in Asia, United States and in Europe. AIXTRON's technology solutions are used by a diverse range of customers worldwide to build advanced components for electronic and opto-electronic applications based on compound, silicon, or organic semiconductor materials. Such components are used in a broad range of innovative applications, technologies and industries. These include LED applications, display technologies, data storage, data transmission, energy management and conversion, communication, signaling and lighting as well as a range of other leading-edge technologies.

Our registered trademarks: AIXACT[®], AIXTRON[®], Atomic Level SolutionS[®], Close Coupled Showerhead[®], CRIUS[®], Gas Foil Rotation[®], Optacap[™], OVPD[®], Planetary Reactor[®], PVPD[®], TriJet[®]

For further information on AIXTRON (FSE: AIXA, ISIN DE000A0WMPJ6; NASDAQ: AIXG, ISIN US0096061041) please visit our website at: www.aixtron.com.

For further information please contact

Corporate Communications

AIXTRON SE, Dornkaulstr. 2, 52134 Herzogenrath, Germany

PHONE +49 (2407) 9030-444 **FAX** +49 (2407) 9030-445

E-MAIL info@aixtron.de **WEB** www.aixtron.com

Forward-Looking Statements

This document may contain forward-looking statements regarding the business, results of operations, financial condition and earnings outlook of AIXTRON within the meaning of the safe harbor provisions of the US Private Securities Litigation Reform Act of 1995. These statements may be identified by words such as "may", "will", "expect", "anticipate", "contemplate", "intend", "plan", "believe", "continue" and "estimate" and variations of such words or similar expressions. These forward-looking statements are based on our current views and assumptions and are subject to risks and uncertainties. You should not place undue reliance on these forward-looking statements. Actual results and trends may differ materially from those reflected in our forward-looking statements. This could result from a variety of factors, such as actual customer orders received by AIXTRON, the level of demand for deposition technology in the market, the timing of final acceptance of products by customers, the condition of financial markets and access to financing for AIXTRON, general conditions in the market for deposition plants and macroeconomic conditions, cancellations, rescheduling or delays in product shipments, production capacity constraints, extended sales and qualification cycles, difficulties in the production process, the general development in the semi-conductor industry, increased competition, fluctuations in exchange rates, availability of public funding, fluctuations and/or changes in interest rates, delays in developing and marketing new products, a deterioration of the general economic situation and any other factors discussed in any reports or other announcements filed by AIXTRON with the U.S. Securities and Exchange Commission. Any forward-looking statements contained in this document are based on current expectations and projections of the executive board and on information currently available to it and are made as at the date hereof. AIXTRON undertakes no obligation to revise or update any forward-looking statements as a result of new information, future events or otherwise, unless expressly required to do so by law.

For further information please contact

Corporate Communications

AIXTRON SE, Dornkaulstr. 2, 52134 Herzogenrath, Germany

PHONE +49 (2407) 9030-444 **FAX** +49 (2407) 9030-445

E-MAIL info@aixtron.de **WEB** www.aixtron.com